IPC ASSOCIATION COI	Material Comp © Copyright 2005. international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				rials and N	ials and Mfg Information			
upplier In	nformation														
Company name*			Company unique ID			J	Unique ID Authority				Respon	Response Date*			
onsemi											2024-0	2024-05-21			
Contact Name			Title - Contact			I	Phone - Contact*				Email	Email - Contact*			
Product-Env	-Stewards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized R	epresentative*	Title - Representative			I	Phone - Representative*				Email	Email - Representative*				
Product-Env	-Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Re	Requester Item Number Mfr Ite		tem Number Mfr Item Name				Effective Date Version Manufacturing		Manufacturing Site		Weight*	UOM	Unit Type		
		TIG065E8-TL-H NCH IGBT 1:		NCH IGBT 150A	150A 400V 2.5V		2024-05-21	05-21 CNG			19.05	mg	Each		
Ianufactu	ring Proccess Informa	ation													
Ter	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 M		-STD-020 MS	SL Rating	Peak Process Body Ter		y Temperatu	perature Max Time at Peak Te		ture Numl	per of Reflow Cyc	eles	
contains Bi		CU Alloy 1			260 C		30	seco	nds 3						
omments															
vel 1 - maxii	mum time at peak temperat	ure during sol	ldering is 10-3	30 seconds											
or more info	ormation regarding materia	l composition	please refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.5	mg	Supplier	Silicon (Si)	7440-21-3		1.5	mg
Die Attach Solder	0.99	mg	Supplier	Silver (Ag)	7440-22-4		0.0247	mg
			A	Lead (Pb)	7439-92-1	7a	0.9158	mg
			Supplier	Tin (Sn)	7440-31-5		0.0495	mg
Lead Frame	8.66		Supplier	Silver (Ag)	7440-22-4		0.0961	mg
			Supplier	Tin (Sn)	7440-31-5		0.0121	mg
			Supplier	Copper (Cu)	7440-50-8		8.5518	mg
Mold Compound-Black	7.75			Epoxy Phenol Resin	proprietary data		0.2945	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0775	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.775	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.425	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		1.1625	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0155	mg
Plating	0.14	mg	В	Bismuth (Bi)	7440-69-9		0.0008	mg
			Supplier	Tin (Sn)	7440-31-5		0.1392	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg